





30V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)}	I _D Τ _A = +25°C
201/	460mΩ @ V _{GS} = 4.5V	0.9A
30V	560mΩ @ V _{GS} = 2.5V	0.7A

Features and Benefits

- 0.5mm ultra low profile package for thin application
- 0.6mm² package footprint, 10 times smaller than SOT23
- Low V_{GS(th)}, can be driven directly from a battery
- Low R_{DS(on)}
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- ESD Protected Gate 2kV
- Qualified to AEC-Q101 Standards for High Reliability

Description and Applications

This MOSFET is designed to minimize the on-state resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Load Switch
- Portable Applications
- Power Management Functions

Mechanical Data

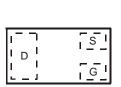
- Case: X1-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound;
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish NiPdAu over Copper Leadframe; Solderable per MIL-STD-202, Method 208 (e4)
- Weight: 0.001 grams (Approximate)



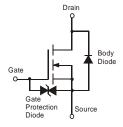




Bottom View



Top View Internal Schematic



Equivalent Circuit

Ordering Information (Note 4)

Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMN3730UFB-7	NE	7	8	3,000
DMN3730UFB-7B	NE	7	8	10,000

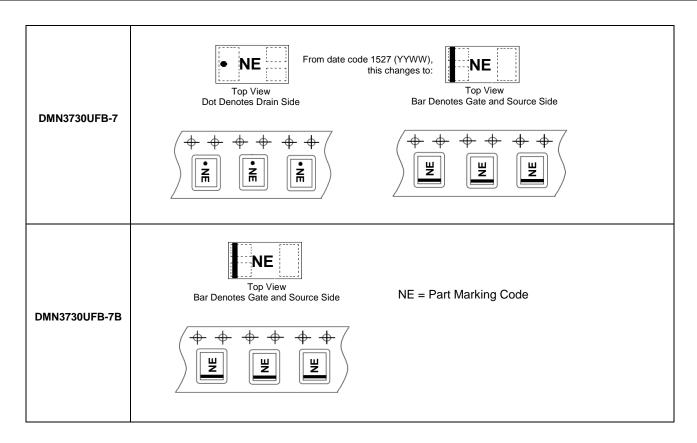
Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

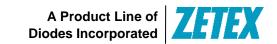




Marking Information







Maximum Ratings (@T_A = +25°C unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	30	V
Gate-Source Voltage	Gate-Source Voltage			±8	V
		(Note 6)	1	0.91	
Continuous Drain Current	$V_{GS} = 4.5V$	$T_A = +70^{\circ}C \text{ (Note 6)}$	ID	0.73	Α
		(Note 5)		0.75	
Pulsed Drain Current (Note 7)		I _{DM}	3	Α	

Characteristic		Symbol	Value	Unit	
Power Dissipation	(Note 6)	Б	0.69	W	
Power Dissipation	(Note 5)	P_{D}	0.47		
Thermal Desigtance Junction to Ambient	(Note 6)	Б	180	°C/W	
Thermal Resistance, Junction to Ambient	(Note 5)	$R_{\theta JA}$	258		
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C	

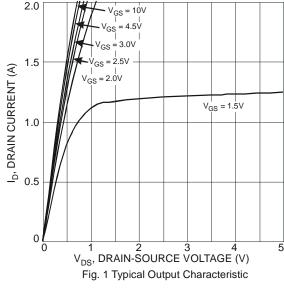
Electrical Characteristics (@T_A = +25°C unless otherwise specified.)

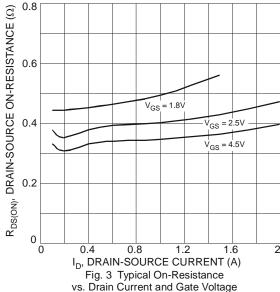
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV _{DSS}	30	-	-	V	$V_{GS} = 0V, I_{D} = 10\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	-	-	1	μΑ	$V_{DS} = 30V$, $V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	ı	-	3	μΑ	$V_{GS} = \pm 8V$, $V_{DS} = 0V$	
ON CHARACTERISTICS							
Gate Threshold Voltage	$V_{GS(th)}$	0.45	-	0.95	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
				460		$V_{GS} = 4.5V, I_D = 200mA$	
Static Drain-Source On-Resistance (Note 8)	R _{DS} (ON)	-	-	560	mΩ	$V_{GS} = 2.5V, I_D = 100mA$	
				730		$V_{GS} = 1.8V, I_D = 75mA$	
Forward Transfer Admittance	Y _{fs}	40	-	-	mS	$V_{DS} = 3V$, $I_D = 10mA$	
Diode Forward Voltage (Note 8)	V _{SD}	-	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 300mA$	
DYNAMIC CHARACTERISTICS (Note 9)						•	
Input Capacitance	Ciss	•	64.3	-	pF)	
Output Capacitance	Coss	ı	6.1	-	pF	$V_{DS} = 25V, V_{GS} = 0V,$ - f = 1.0MHz	
Reverse Transfer Capacitance	Crss	ı	4.5	-	рF	1 = 1.000112	
Gate Resistance	Rg	•	70	-	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Q_g	1	1.6	-	nC	\\\\ 4.5\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	
Gate-Source Charge	Qgs	-	0.2	-	nC	$V_{GS} = 4.5V, V_{DS} = 15V,$ $I_{D} = 1A$	
Gate-Drain Charge	Q_{gd}	-	0.2	-	nC		
Turn-On Delay Time	t _{D(on)}	ı	3.5	-	ns	V _{DS} = 10V, I _D = 1A	
Turn-On Rise Time	t _r	-	2.8	-	ns		
Turn-Off Delay Time	t _{D(off)}	ı	38	-	ns	$V_{GS} = 10V$, $R_G = 6\Omega$	
Turn-Off Fall Time	t _f	ı	13	-	ns		

Notes:

- 5. For a device surface mounted on a minimum recommended pad layout of an FR4 PCB, in still air conditions; the device is measured when operating in steady-state condition.
- 6. Same as Note 5, except the device measured at $t \le 10$ seconds.
- 7. Same as Note 5, except the device is pulsed at duty cycle of 1% for a pulse width of 10µs.
- 8. Measured under pulsed conditions to minimize self-heating effect. Pulse width \leq 300 μ s; duty cycle \leq 2%.
- 9. For design aid only, not subject to production testing.







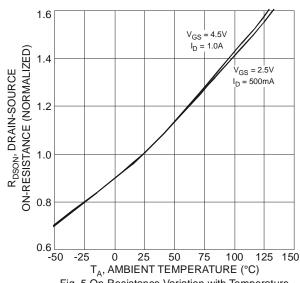
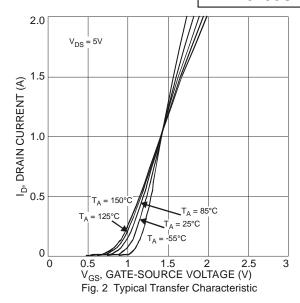
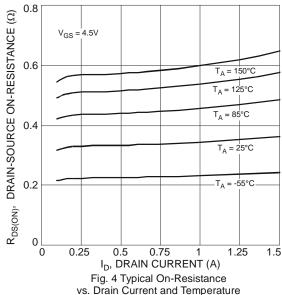
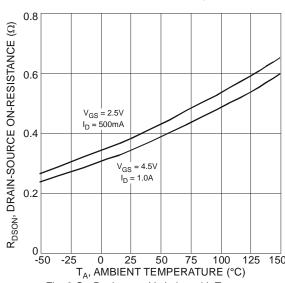


Fig. 5 On-Resistance Variation with Temperature









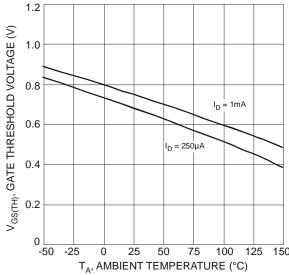
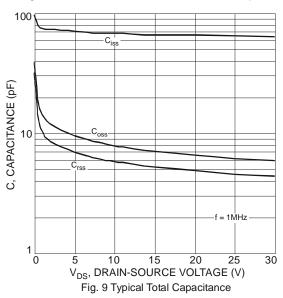
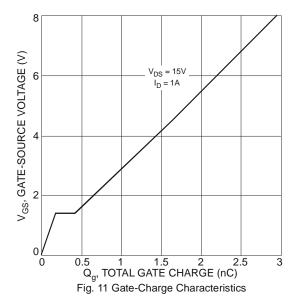
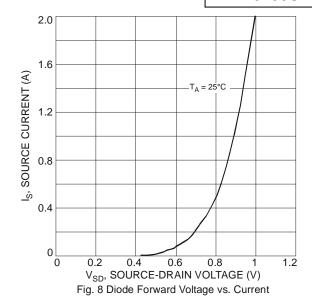
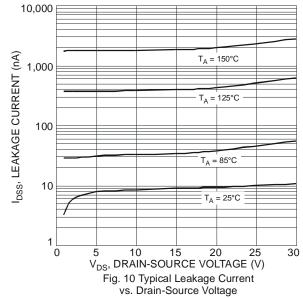


Fig. 7 Gate Threshold Variation vs. Ambient Temperature











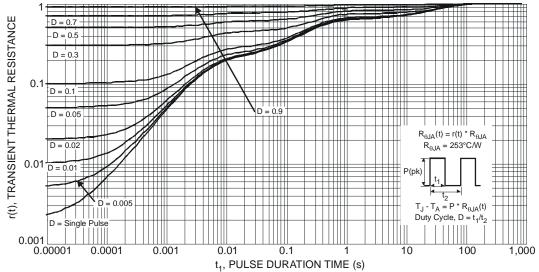


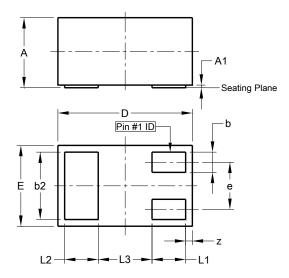
Fig. 12 Transient Thermal Response





Package Outline Dimensions

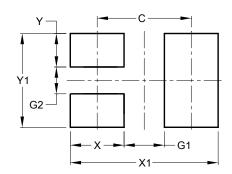
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



X1-DFN1006-3					
Dim	Min	Max	Тур		
Α	0.47	0.53	0.50		
A1	0.00	0.05	0.03		
b	0.10	0.20	0.15		
b2	0.45	0.55	0.50		
D	0.95	1.075	1.00		
E	0.55	0.675	0.60		
е	ı	-	0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
L3	-	-	0.40		
Z	0.02	0.08	0.05		
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.70
G1	0.30
G2	0.20
Х	0.40
X1	1.10
Y	0.25
V1	0.70





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